

# Signal Integrity and Radiated Emission

of High-Speed Digital Systems

SPARTACO CANIGGIA  
FRANCESCA ROMANA MARADEI

 WILEY

# **SIGNAL INTEGRITY AND RADIATED EMISSION OF HIGH-SPEED DIGITAL SYSTEMS**

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*Italtel (retired) and Expert of Comitato Elettrotecnico Italiano (CEI), Italy*

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# Contents

<b>List of Examples</b>	<b>xiii</b>
<b>Foreword</b>	<b>xvii</b>
<b>Preface</b>	<b>xix</b>
<b>1 Introduction to Signal Integrity and Radiated Emission in a Digital System</b>	<b>1</b>
1.1 Power and Signal Integrity	2
1.1.1 Power Distribution Network	3
1.1.2 Signal Distribution Network	5
1.1.3 Noise Limitations and Design for Characteristic Impedance	7
1.2 Radiated Emission	9
1.2.1 Definition of Radiated Emission Sources	9
1.2.2 Radiated Emission Standards	11
1.2.3 Radiated Emission from a Real System	17
1.3 Signaling and Logic Devices	19
1.3.1 Overshoot, Undershoot and Plateau	20
1.3.2 Noise Immunity	24
1.3.3 Timing Parameters	25
1.3.4 Eye Diagram	27
1.4 Modeling Digital Systems	29
1.4.1 Mathematical Tools	29
1.4.2 Spice-Like Circuit Simulators	30
1.4.3 Full-Wave Numerical Tools	31
1.4.4 Professional Simulators	34
References	34
<b>2 High-Speed Digital Devices</b>	<b>37</b>
2.1 Input/Output Static Characteristic	37
2.1.1 Current and Voltage Specifications	37
2.1.2 Transistor–Transistor Logic (TTL) Devices	39
2.1.3 Complementary Metal Oxide Semiconductor (CMOS) Devices	42
2.1.4 Emitter-Coupled Logic (ECL) Devices	44
2.1.5 Low-Voltage Differential Signal (LVDS) Devices	45
2.1.6 Logic Devices Powered and the Logic Level	45
2.2 Dynamic Characteristics: Gate Delay and Rise and Fall Times	46



2.3	Driver and Receiver Modeling	48
2.3.1	<i>Types of Driver Model</i>	48
2.3.2	<i>Driver Switching Currents Path</i>	50
2.3.3	<i>Driver Non-Linear Behavioral Model</i>	51
2.3.4	<i>Receiver Non-Linear Behavioral Modeling</i>	53
2.4	I/O Buffer Information Specification (IBIS) Models	54
2.4.1	<i>Structure of an IBIS Model</i>	54
2.4.2	<i>IBIS Models and Spice</i>	56
	References	58
<b>3</b>	<b>Inductance</b>	<b>59</b>
3.1	Loop Inductance	59
3.1.1	<i>Inductances of Coupled Loops</i>	60
3.1.2	<i>Inductances of Thin Filamentary Circuits</i>	62
3.1.3	<i>Equivalent Circuit of Two Coupled Loops</i>	62
3.1.4	<i>L Matrix of Two Coupled Conductors Having a Reference Return Conductor</i>	63
3.1.5	<i>L Calculation of a Three-Conductor Wire-Type Line</i>	65
3.1.6	<i>Frequency-Dependent Internal Inductance</i>	66
3.2	Partial Inductance	67
3.2.1	<i>Partial Inductances of Coupled Loops</i>	67
3.2.2	<i>Flux Area of Partial Inductance of Thin Filamentary Segments</i>	68
3.2.3	<i>Loop Inductance Decomposed into Partial Inductances</i>	70
3.2.4	<i>Self and Mutual Partial Inductance</i>	72
3.2.5	<i>Inductance Between Two Parallel Conductors</i>	74
3.2.6	<i>Loop Inductance Matrix Calculation by Partial Inductances</i>	75
3.2.7	<i>Partial Inductance Associated with a Finite Ground Plane</i>	76
3.2.8	<i>Solving Inductance Problems in PCBs</i>	77
3.3	Differential Mode and Common Mode Inductance	79
3.3.1	<i>Differential Mode Inductance</i>	79
3.3.2	<i>Common Mode Inductance</i>	80
	References	81
<b>4</b>	<b>Capacitance</b>	<b>83</b>
4.1	Capacitance Between Conductors	83
4.1.1	<i>Definition of Capacitance</i>	83
4.1.2	<i>Partial Capacitance and Capacitance Matrix of Two Coupled Conductors Having a Reference Return Conductor</i>	85
4.1.3	<i>Capacitance Matrix of n Coupled Conductors Having a Reference Return Conductor</i>	86
4.2	Differential Mode and Common Mode Capacitance	87
4.2.1	<i>Differential Mode Capacitance</i>	87
4.2.2	<i>Common Mode Capacitance</i>	88
	References	89

---

<b>5</b>	<b>Reflection on Signal Lines</b>	<b>91</b>
5.1	Electrical Parameters of Interconnects	91
5.1.1	<i>Typical Interconnects</i>	91
5.1.2	<i>Equivalent Circuit of a Short Interconnect</i>	92
5.1.3	<i>Lossless Transmission Lines</i>	94
5.1.4	<i>Transmission-Line Modeling by Using Partial Inductances</i>	96
5.2	Incident and Reflected Waves in Lossless Transmission Lines	96
5.2.1	<i>Resistive Discontinuity</i>	97
5.2.2	<i>Capacitive Discontinuity</i>	97
5.2.3	<i>Reflections in Interconnects Terminated with Resistive Loads</i>	99
5.2.4	<i>Critical Length of Interconnects</i>	100
5.2.5	<i>Lattice Diagram for Reflection Calculation</i>	101
5.2.6	<i>Exact Model of a Lossless Transmission Line</i>	102
5.2.7	<i>Graphical Solution for Line Voltages</i>	105
5.3	Signal Distribution Architecture	109
5.3.1	<i>Point-to-Point Structure</i>	110
5.3.2	<i>Star Structure</i>	110
5.3.3	<i>Chain Structure</i>	111
5.3.4	<i>Bus Structure</i>	112
5.3.5	<i>H-Tree Structure</i>	112
5.3.6	<i>Comb Structure</i>	112
5.4	Line Terminations	114
5.4.1	<i>Thévenin Termination</i>	114
5.4.2	<i>Series, Parallel, and AC Terminations</i>	117
5.4.3	<i>Series Termination and Comparison with Other Terminations by Circuit Simulations</i>	117
5.4.4	<i>Thévenin Termination Applied to Chain Structures and Circuit Simulations</i>	118
5.4.5	<i>Series Termination Applied to Chain Structures and Circuit Simulations</i>	120
5.4.6	<i>Thévenin Termination Applied to Bus Structures and Circuit Simulations</i>	121
5.4.7	<i>Termination and Interconnection Structures</i>	123
5.4.8	<i>Termination Performance</i>	123
	References	124
<b>6</b>	<b>Crosstalk</b>	<b>125</b>
6.1	Lumped-Circuit Model of Coupled Lines	126
6.1.1	<i>Equivalent Circuit of Two Coupled Lines with a Reference Ground</i>	126
6.1.2	<i>Capacitive Coupling</i>	127
6.1.3	<i>Inductive Coupling</i>	129
6.1.4	<i>Total Coupling</i>	130
6.1.5	<i>Simulations of Two Coupled Lines</i>	130
6.2	Common and Differential Modes	133
6.2.1	<i>Definition of Even and Odd Modes</i>	134
6.2.2	<i>Equivalent Circuit Based on Even and Odd Modes</i>	136

6.2.3	<i>Equivalent Circuit for the Differential Transmission Mode</i>	137
6.2.4	<i>Simulations of Point-to-Point and Chain Structure by Even and Odd Modes</i>	137
6.3	Models for Digital Devices: Simulation and Measurements	140
6.4	General Distributed Model for Lossless Multiconductor Transmission Lines	150
6.4.1	<i>Equivalent Circuit of n Coupled Lossless Lines</i>	151
6.4.2	<i>Measurements and Simulations of Five Coupled Lines with TTL and CMOS Devices</i>	152
6.5	Techniques to Reduce Crosstalk	157
6.5.1	<i>Fixes to Reduce Crosstalk</i>	157
6.5.2	<i>Simulations of Coupled Lines with Grounded Traces used as a Shield</i>	158
6.5.3	<i>Full-Wave Numerical Simulations of Two Coupled Lines</i>	158
	References	161
<b>7</b>	<b>Lossy Transmission Lines</b>	<b>163</b>
7.1	Lossy Line Fundamental Parameters	164
7.1.1	<i>Reflection Mechanism in a Lossy Line</i>	164
7.1.2	<i>Skin Effect</i>	167
7.1.3	<i>Proximity Effect</i>	171
7.1.4	<i>Lossy Dielectric Effect</i>	173
7.1.5	<i>Data Transmission with Lossy Lines</i>	175
7.2	Modeling Lossy Lines in the Time Domain by the Segmentation Approach and Vector Fitting Technique	183
7.2.1	<i>Circuit Extraction of Coaxial Cables</i>	184
7.2.2	<i>Circuit Extraction of Twisted-Pair Cables</i>	195
7.3	Modeling Lossy Lines in the Time Domain by the Scattering Parameters Technique	207
7.4	Conclusions	215
	References	216
<b>8</b>	<b>Delta I-Noise</b>	<b>219</b>
8.1	Switching Noise	220
8.1.1	<i>Power Distribution Network</i>	220
8.1.2	<i>Switching Current Path</i>	225
8.1.3	<i>Design Rules</i>	236
8.2	Filtering Power Distribution	237
8.2.1	<i>Filtering Multilayer PCBs</i>	237
8.2.2	<i>Measurement of Power Distribution Network Impedance</i>	244
8.2.3	<i>PCB Circuit Model Based on Radial Transmission Line Theory</i>	245
8.3	Ground Bounce	254
8.3.1	<i>Ground Bounce Mechanism</i>	255
8.3.2	<i>Circuit Simulations to Understand the Ground Bounce Mechanism</i>	256
8.3.3	<i>Measurements of an LVT Benchmark</i>	257
8.4	Crosstalk and Switching Noise	262
8.4.1	<i>Measurements and Simulations of the SQ-Test Board with Three Coupled Lines and 74AC04 Devices</i>	262
	References	266

---

<b>9 PCB Radiated Emission</b>	<b>269</b>
9.1 Frequency Characterization of a Digital Signal	270
9.1.1 <i>Spectrum of a Trapezoidal Waveform</i>	270
9.1.2 <i>Spectrum of Typical Noises</i>	274
9.2 The Radiated Emission Problem	276
9.2.1 <i>Radiation from a Wire Antenna</i>	278
9.2.2 <i>Common- and Differential-Mode Currents and Radiations</i>	279
9.2.3 <i>Emission Due to Line Asymmetrical Feed</i>	281
9.2.4 <i>Differential-Mode Current and Radiated Emission of a Transmission Line</i>	282
9.2.5 <i>Common-Mode Current and Radiated Emission of a Transmission Line</i>	284
9.2.6 <i>Image Plane</i>	287
9.3 Emission from Traces	289
9.3.1 <i>Antenna Models for Calculating the Radiation of Microstrip and Stripline Structures</i>	289
9.4 Emission from ICs	295
9.4.1 <i>Radiated Emission Mechanism from Components in a PCB</i>	296
9.5 Emission from a Real PCB	298
9.6 Emission from a PCB with an Attached Cable	303
9.6.1 <i>Sources of Emission</i>	303
9.6.2 <i>Current- and Voltage-Driven Mechanisms with a Trace in a PCB</i>	303
9.7 Differential Drivers as Sources of Emission	318
9.7.1 <i>Common-Mode Current with Differential Drivers</i>	318
9.7.2 <i>Radiated Field Mechanism of UTP and SFTP Cables</i>	319
9.8 Emission from a Complex System	327
9.8.1 <i>Emission Model of Coaxial Cables</i>	330
9.8.2 <i>Low-Frequency Model of an Aperture</i>	336
9.9 Radiation Diagrams	341
9.10 Points to Remember and Design Rules for Radiated Emission	349
References	352
<b>10 Grounding in PCBs</b>	<b>355</b>
10.1 Common-Mode Coupling	355
10.1.1 <i>What is Ground?</i>	356
10.1.2 <i>Ground Loop Coupling and Transfer Impedance</i>	356
10.1.3 <i>Grounding Strategy</i>	363
10.2 Ground and Power Distribution in a Multilayer PCB	365
10.2.1 <i>Return Path for the Signal</i>	366
10.2.2 <i>Power (PWR) and Ground (GND) Layer Planning and Topology</i>	370
10.2.3 <i>Trace Changing Reference Plane</i>	370
10.2.4 <i>Split Power Plane</i>	372
10.2.5 <i>Moats/Barriers and Bridges</i>	373
10.2.6 <i>Stitches</i>	374
10.3 Grounding at PCB Connectors	375
10.3.1 <i>Ground Noise and Transfer Impedance</i>	375

10.3.2	<i>Pin Assignment</i>	381
10.3.3	<i>Grounding a PCB to a Chassis</i>	384
10.3.4	<i>Techniques to Limit Emission from Cables</i>	385
10.4	Partitioning and Modeling	393
10.4.1	<i>Modeling the Power Distribution with a Driver for Simulations</i>	400
10.5	Points to Remember and Design Rules for Grounding in PCBs	402
	References	406
<b>11</b>	<b>Measurement and Modeling</b>	<b>409</b>
11.1	Time-Domain Reflectometer (TDR)	410
11.1.1	<i>TDR as a ‘Closed-Loop Radar’</i>	410
11.1.2	<i>TDR Resolution and Aberrations</i>	412
11.1.3	<i>TDR and Lossy Lines</i>	415
11.1.4	<i>Differential TDR</i>	416
11.2	Vector Network Analyzer (VNA)	417
11.2.1	<i>Scattering Parameter Definition</i>	417
11.2.2	<i>VNA Calibration</i>	420
11.2.3	<i>Extraction of Equivalent Circuits by S-Parameter Simulations</i>	421
11.2.4	<i>Conclusions Concerning VNA Measurements and Simulations</i>	429
11.3	Prediction Model Validation by Radiated Emission Measurements	431
11.3.1	<i>Uncertainty of the EMC Lab for Radiated Field Measurements and Numerical Simulations</i>	431
11.3.2	<i>Modeling the Radiating Source</i>	436
11.3.3	<i>Conclusion Concerning Validation of the Numerical Prediction Model for Radiated Emission by Comparison with Measurements</i>	439
	References	440
<b>12</b>	<b>Differential Signaling and Discontinuity Modeling in PCBs</b>	<b>441</b>
12.1	Differential Signal Transmission	442
12.1.1	<i>Single-Ended Versus Differential Signal Transmission</i>	442
12.1.2	<i>Differential Interconnect with Traces in PCBs and the ATCA Standard</i>	445
12.1.3	<i>Differential Devices: Signal Level Comparison</i>	447
12.1.4	<i>Differential Signal Distribution and Terminations</i>	447
12.1.5	<i>LVDS Devices</i>	451
12.2	Modeling Packages and Interconnect Discontinuities in PCBs	466
12.2.1	<i>Multilayer Boards</i>	466
12.2.2	<i>Bends</i>	466
12.2.3	<i>Serpentines</i>	468
12.2.4	<i>Ground Slot</i>	468
12.2.5	<i>Vias</i>	471
12.2.6	<i>Connectors</i>	473
12.2.7	<i>IC Package</i>	475
	References	477
<b>Appendix A</b>	<b>Formulae for Partial Inductance Calculation</b>	<b>481</b>
A.1	Round Wires	481

---

A.2 Busbars	483
A.3 Examples of Application of the Inductance Formulae	485
References	485
<b>Appendix B Characteristic Impedance, Delay Time, and Attenuation of Microstrips and Striplines</b>	<b>487</b>
B.1 Microstrip	487
B.2 Stripline	489
B.3 Trace Attenuation and the Proximity-Effect Parameter	490
References	492
<b>Appendix C Computation of Resonances in the Power Distribution Network of a PCB</b>	<b>493</b>
C.1 Cavity Model	493
C.2 Spice Model	497
C.3 Numerical Model	498
C.4 Results of the Simulations	498
References	500
<b>Appendix D Formulae for Simple Radiating Structures</b>	<b>501</b>
D.1 Wire Structures	501
D.2 Wires and Ground Planes	503
D.3 Emission from Apertures	505
References	505
<b>Appendix E The Nodal Method to Calculate the Partial Inductance of Finite Ground Planes</b>	<b>507</b>
E.1 Nodal Method Equations	507
E.2 Nodal Method Applied to Compute the Partial Inductance Associated with a Finite Ground Plane	508
References	511
<b>Appendix F Files on the Web</b>	<b>513</b>
F.1 Program Files of Chapter 1	513
F.2 Program Files of Chapter 2	513
F.3 Program Files of Chapter 5	513
F.4 Program Files of Chapter 6	514
F.5 Program Files of Chapter 7	514
F.6 Program Files of Chapter 8	515
F.7 Program Files of Chapter 9	516
F.8 Program Files of Chapter 10	517
<b>Index</b>	<b>519</b>



# List of Examples

Example 3.1: Calculation of Inductances Associated with the Decoupling Capacitor and IC Device in a PCB	77
Example 5.1: Measurements and Graphical Method Applied to an Interconnection with TTL Devices	107
Example 6.1: Point-to-Point Structure	131
Example 6.2: Chain Structure	133
Example 6.3: Two Coupled Lines with Linear Loads	137
Example 6.4: Two Coupled Traces with TTL Devices in a Point-to-Point Test Board Structure	140
Example 6.5: Two Coupled Lines in a Bus Test Board Structure	144
Example 6.6: Five Coupled Lines with Non-linear Loads	152
Example 7.1: Trace with 50 $\Omega$ Characteristic Impedance	178
Example 7.2: Signal Integrity in a Lossy Coaxial Cable	192
Example 7.3: Signal Integrity in a Lossy UTP Cable	197
Example 7.4: Eye Diagram of a 75m Unshielded Twisted-pair Cable Driven by an RS422 Device	201
Example 7.5: Coaxial Cable Driven by an Ultrawide-band Signal Simulated by the TL Model Based on the Time-domain S-parameters	213
Example 8.1: Switching Noise Simulations of Two Stripline and Microstrip Structures	227
Example 8.2: Test Board for Prediction of Power Bus Impedance by Several Methods	239
Example 8.3: Measurements and Simulations with Standard Buried Capacitance (SBC) Test Boards	247
Example 9.1: Computations and Measurements of a Clock Spectrum	272
Example 9.2: Calculations and Measurements of Emission Produced by P-Test Boards	285
Example 9.3: Calculations and Measurements of Emission from S-Test Boards	292
Example 9.4: Calculations and Measurements of Emission from A-Test Boards	294
Example 9.5: Calculations and Measurements of Emission from Multilayer SBC-Test Boards	296
Example 9.6: Calculations and Measurements on a Test Board Equipped with CMOS Devices Interconnected by a Star Structure	299
Example 9.7: Calculations and Measurements of Emission from Simple Test Boards (P-Boards) with an Attached Cable	307



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Example 9.8:	Calculations and Measurements of Emission from S-Test Boards with an Attached Cable	311
Example 9.9:	Calculations and Measurements of Emission from A-Test Boards with an Attached Cable	313
Example 9.10:	Calculations and Measurements of Emission from SBC-Test Boards with an Attached Cable due to the Voltage-driven Mechanism	314
Example 9.11:	Calculations and Measurements of Emission from D-Test Boards with Differential Drivers and Receivers Interconnected by UTP and SFTP Cables	320
Example 9.12:	Measurements of Emission from a Shielded Rack Equipped with PCBs and Power Supply	328
Example 9.13:	Calculations and Measurements of Radiated Emission from a Coaxial Cable	333
Example 9.14:	Measurements of Radiation from UTP Cable Filtered with a Common-mode Choke	334
Example 9.15:	Calculations and Measurements of Radiation from P-Test Boards within a Shielded Rack with a Rectangular Aperture	338
Example 9.16:	Measurement of Radiated Emission Patterns from Telecommunication Equipment	342
Example 9.17:	Computation of Radiation from a Wire above a Finite Ground Plane with an Attached Cable	344
Example 10.1:	Computation of Transfer Impedance for Several Interconnection Structures	361
Example 10.2:	Current Distribution and Radiation Pattern for Microstrip- and Stripline-like Structures	366
Example 10.3:	Calculation of the Noise in a Connector with an ECL Device	377
Example 10.4:	Calculation of Noise in a Connector using SPICE	377
Example 10.5:	Measurements of Transfer Impedance for Three Test Connectors	380
Example 10.6:	Measurements of Radiation from a Test Cable with a Pigtail	382
Example 10.7:	Numerical Simulations of a Test Board with an Attached Cable	386
Example 10.8:	S-parameter Measurements and Simulations of a Test Board with a Split	393
Example 10.9:	S-parameter Measurements and Simulations of a Test Board with an Island	398
Example 11.1:	Simulation of TDR Measurements Assuming a Trace in a PCB as the DUT	411
Example 11.2:	Simulation of TDR Measurements Assuming a Via as the DUT	414
Example 11.3:	Transmission-line Parameter Extraction of a Simple Connector	423
Example 11.4:	Lumped-circuit Element Extraction of a Simple Via	426
Example 11.5:	Radiated Emission Measurements from a Rack in Two Different Semi-anechoic Rooms	431
Example 11.6:	Modeling a Radiating Loop in a Semi-anechoic Room	436
Example 12.1:	LVDS Signal Integrity and Common-mode Rejection Investigation by Measurements	451

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Example 12.2: LVDS Crosstalk Investigation by Simulations	458
Example 12.3: Characterization of a Backplane for High-speed Application up to 3.125 GHz by Measurements	459
Example 12.4: Numerical Simulation of the Distortion Introduced on Signals by a Slot in the Ground Plane	469